

## **RX Family**

List of Firmware Integration Technology modules included with RX Driver Package

### Introduction

This application note indicates Firmware Integration Technology (FIT) module version included with RX Driver Package (RDP).

### **Target Device**

RX Family MCU corresponding to FIT module.

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### 1. Overview

Indicates FIT module version included with RDP.

### 2. List of FIT modules included with RX Driver Package

List of FIT modules included with RDP in the table below.

Table 2.1 List of device driver included with RDP

FIT Module	Document Number												RDP											
		1.10	1.11	1.12	1.13	1.14	1.15	1.16	1.17	1.18	1.19	1.20	1.22	1.23	1.24	1.25	1.26	1.27	1.28	1.30	1.31	1.32	1.33 1.	.34
BSP	R01AN1685	3.31	3.40	3.50	3.60	3.71	3.71	3.91	3.91	3.91	4.01	5.20	5.20	5.40	5.50	5.52	5.52	5.61	5.63	5.66	6.11	6.21	7.00 7.	.10
LVD		1.50			2.30		2.31		2.41		2.50		3.20					3.60	3.60	3.60	3.70		3.90 4.	_
LPC	R01AN2769	-	-	1.40	1.40	1.40	1.40	1.40	1.40	1.40	1.40	1.41	1.41	2.00	2.00	2.00	2.00	2.01	2.01	2.01	2.02	2.03	2.03 2.	.03
VBATT	R01AN2796	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.02	1.03	1.04	1.04	1.04	1.04	1.04	1.05	1.05	1.05	2.00	2.00	2.10 2.	.10
IRQ	R01AN1668	1.90	2.00	2.10	2.20	2.21	2.21	2.30	2.31	2.31	2.40	3.00	3.20	3.20	3.30	3.40	3.50	3.60	3.60	3.60	3.70	3.80	3.90 4.	.00
DTC	R01AN1819	2.04	2.05	2.07	2.08	2.08	2.08	2.09	2.09	2.09	2.20	3.00	3.20	3.21	3.30	3.40	3.50	3.60	3.60	3.60	3.70	3.80	3.90 4.	.00
DMAC		1.03	1.04		1.05	1.05	1.05	1.06	1.06	1.06	1.20		2.20			2.30	2.40	2.50	2.50	2.50	2.60		2.70 2.	_
GPIO			-	_	2.30	2.31	2.31			2.41	2.50		3.20		_	3.40		3.60	3.70	3.90	4.00			.40
MPC	R01AN1724	_			2.30		2.31		2.41		2.50		3.20	_	_				3.60	3.80	3.90		4.10 4.	_
CMT	R01AN1856		3.00		3.20	3.21	3.21		3.31	3.31	3.40		4.20			4.31	4.40	4.70	4.70	4.70	4.80			.10
CMTW RTC		1.10 2.41	1.20 2.50	1.20 2.50	1.30 2.71	1.31 2.72	1.31 2.72		1.32 2.73	1.32 2.73	1.40 2.74		2.10			2.20	2.20 2.78	2.30	2.30	2.30	2.40			.50 .82
LPT	R01AN2571	1.00	1.10	1.11	1.20	1.21	1.21	1.21	1.22	1.22	1.22	1.23	1.23	1.23		1.23		2.79	2.01	2.01	2.01		3.00 3.	_
IWDT		1.51			1.80		1.81	1.90	1.91	1.91	2.00		3.20			3.40		3.60	3.60	3.60	3.70		3.90 4.	
WDT	R01AN3200	-	1.00	1.00	1.10	1.20	1.20	1.30	1.31	1.31	1.40		2.20	2.20	2.20	2.30	2.30	2.40	2.40	2.40	2.50			.70
SCI		1.70	1.80	_	2.00	2.01	2.01	2.10	2.11	2.11	2.20		3.20	3.20	_	3.40	3.50	3.70	3.70	3.70	3.80		4.10 4.	.30
RSCI	R01AN5759	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	2.00 2.	.00
SCIFA	R01AN2222	1.10	1.10	1.10	1.20	1.20	1.20	1.20	1.20	1.20	1.20	1.22	1.22	1.22	1.22	2.00	2.00	2.00	2.01	2.01	2.01	2.01	2.01 2.	.01
SCI-IIC	R01AN1691	1.90	2.00	2.00	2.20	2.20	2.20	2.20	2.31	2.31	2.40	2.41	2.43	2.43	2.45	2.45	2.46	2.46	2.47	2.47	2.48	2.49	2.49 2.	.49
RIIC	R01AN1692	-	2.00	2.00	2.20	2.20	2.20	2.20	2.31	2.31	2.40	2.41	2.43	2.43	2.45	2.45	2.46	2.46	2.47	2.47	2.48	2.49	2.49 2.	.49
RIICHS	R01AN5552	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00			.00
RSPI	R01AN1827	-	1.50	1.60	1.70	1.70	1.70	1.80	1.80	1.80	2.00	2.01	2.03	2.03	2.04	2.04	2.05	3.00	3.00	3.00	3.01		3.03 3.	_
RSPIA	R01AN5684	-	-	-	- 1 10	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00			.10
QSPI	R01AN1940	1.08	1.09	1.09	1.10	1.10	1.10		1.10	1.10	1.11	1.12	1.13	1.13		1.14	1.14	1.14	1.14	1.14	1.14			.15
QSPIX USB Basic	R01AN5685 R01AN2025	- 1.11	1.20	1.20	1.22	1.23	1.23	1.23	1.23	1.23	1.25	1.26	- 1.27	1.27	- 1.27	1.30	1.30	1.30	1.30	1.30	1.31			.20
USB Basic Mini	R01AN2166	1.02	1.02	1.02	1.02	1.02	1.02	1.10	1.10	1.10	1.10	1.11	1.12	1.12	1.12	1.12	1.12	1.20	1.20	1.20	1.20	1.20		.20
USB HMSC	R01AN2026	1.11	1.20	1.20	1.22	1.23	1.23	1.23	1.23	1.23	1.25		1.27	1.27		1.30	1.30	1.30	1.30	1.30	1.31	1.31		.31
USB HMSC Mini		1.02			1.02	1.02	1.02		1.10	1.10	1.10		1.12	1.12		1.12	1.12	1.20	1.20	1.20	1.20			.20
USB HCDC	R01AN2027	1.11	1.20	1.20	1.22	1.23	1.23	1.23	1.23	1.23	1.25	1.26	1.27	1.27	1.27	1.30	1.30	1.30	1.30	1.30	1.31	1.31		.31
USB HCDC Mini	R01AN2167	1.02	1.02	1.02	1.02	1.02	1.02	1.10	1.10	1.10	1.10	1.11	1.12	1.12	1.12	1.12	1.12	1.20	1.20	1.20	1.20	1.20	1.20 1.	.20
USB HHID	R01AN2028	1.11	1.20	1.20	1.22	1.23	1.23	1.23	1.23	1.23	1.25	1.26	1.27	1.27	1.27	1.30	1.30	1.30	1.30	1.30	1.31	1.31	1.31 1.	.31
USB HHID Mini	R01AN2168	1.02	1.02	1.02	1.02	1.02	1.02	1.10	1.10	1.10	1.10	1.11	1.12	1.12	1.12	1.12	1.12	1.20	1.20	1.20	1.20	1.20	1.20 1.	.20
USB PMSC	R01AN2029	1.11		_	1.22	1.23	1.23	1.23	1.23	1.23	1.25		1.27	1.27	_	1.30	1.30	1.30	1.30	1.30	1.31	1.31		.31
USB PMSC Mini	R01AN2172	1.02	1.02	1.02	1.02	1.02	1.02	1.10	1.10	1.10	1.10		1.12	1.12		1.12	1.12	1.20	1.20	1.20	1.20			.20
USB PCDC	R01AN2030	1.11	1.20	1.20	1.22	1.23	1.23	1.23	1.23	1.23	1.25	1.26	1.27	1.27	1.27	1.30	1.30	1.30	1.30	1.30	1.31	1.31		.31
USB PCDC Mini USB PHID	R01AN2170	1.02	1.02	1.02	1.02	1.02	1.02	1.10	1.10	1.10	1.10	1.11	1.12 1.27	1.12	_	1.12	1.12	1.20	1.20	1.20	1.20	1.20		.20
USB PHID Mini	R01AN2663 R01AN2171	1.11	1.20	1.20	1.02	1.02	1.23	1.10	1.10	1.10	1.10	1.26 1.11	1.12	1.27		1.30	1.12	1.20	1.20	1.30	1.20			.31
EPTPC	R01AN1943	1.11	1.11	1.12	1.14	1.14	1.14		1.14	1.14	1.14		1.12		_	1.12	1.17	1.17	1.17	1.17	1.17			.17
EPTPC Light	R01AN3035		1.10	1.11	1.11	1.11	1.11	1.11	1.11	1.11	1.11		1.13	1.13		1.13	1.14	1.14	1.14	1.14	1.14			.14
ETHERC		1.10	1.11	1.12	1.13	1.14	1.14	1.14	1.14	1.14	1.14		1.17	1.17		1.20	1.20	1.21	1.21	1.21	1.21	1.21	1.22 1.	.22
CAN	R01AN2472			2.10													3.20			5.00			5.20 5.	
RSCAN	R01AN2805																							
IrDA	R01AN2175													_										_
PDC	R01AN3167																							
SDHI	R01AN3852		-																				2.07 2.	
SDSI	R01AN3238		-																				2.02 2.	
MMCIF	R01AN4234		-	-	-	-	-	-	-	-													1.07 1.	
DSMIF S12AD	R01AN4707 R01AN1666		- 0.44	-	- 20	-	- 20	- 2.00	- 2.04	- 2.04	- 2.40	- 4.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00 1.	.00
DAC	R01AN1818																							
Flash	R01AN2184																							
SRC	R01AN2090																							
SSI	R01AN2150													_									2.03 2.	_
TSIP	R20AN0548		-	-	-	-	-	-	-	-	-	-	-	-	-	-							1.14 1.	
LCDC	R01AN1980		1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.01	1.01	1.01	1.01	1.01								
GLCDC	R01AN3609	-	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.01	1.10	1.20	1.20	1.20	1.30	1.30	1.40	1.40	1.50	1.50	1.50	1.50 1.	.50
Unique ID	R01AN2191																							
BYTEQ	R01AN1683																							
LONGQ	R01AN1889	1.60	1.60	1.60	1.60	1.60	1.60	1.70	1.71	1.71	1.71	1.80	1.80	1.80	1.80	1.80	1.80	1.81	1.82	1.82	1.82	1.83	1.90 1.	.90

FIT Module	Document Number												RDP											
		1.10	1.11	1.12	1.13	1.14	1.15	1.16	1.17	1.18	1.19	1.20	1.22	1.23	1.24	1.25	1.26	1.27	1.28	1.30	1.31	1.32	1.33	1.34
QE CTSU	R01AN4469	-	-	-	-	-	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.10	1.10	1.11	1.11	1.11	1.11	2.00	2.00	2.01	2.10
ELC	R01AN3066	-	1.10	1.10	1.20	1.20	1.20	1.20	1.20	1.20	1.20	1.21	1.21	1.21	1.21	1.21	1.21	2.00	2.00	2.00	2.00	2.01	2.01	2.01
DRW2D	R01AN5373	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.10	1.10	1.10	1.11	1.11	1.11	1.11

Table 2.2 List of middleware included with RDP

FIT Module	Document number												RDP											
		1.10	1.11	1.12	1.13	1.14	1.15	1.16	1.17	1.18	1.19	1.20	1.22	1.23	1.24	1.25	1.26	1.27	1.29	1.30	1.31	1.32	1.33	1.34
TCP/IP for Embedded	R20AN0051	2 05	2 05	2 06	2 06	2 07	2 07	2 07	2 08	2 08	2 08	2 08	2 09	2 09	2 09	2 09	2 09	2 09	2 09	2 10	2 10	2 10	2 10	2 10
system M3S-T4-Tiny Module		2.00		2.00			2.01	2.0.	2.00	2.00	2.00	2.00		2.00	2.00	2.00		2.00		2		20	20	
Interface conversion	R20AN0311	1.04	1.05	1.06	1.06	1.06	1.06	1.06	1.07	1.07	1.07	1.07	1.08	1.08	1.08	1.08	1.08	1.08	1.08	1.09	1.09	1.09	1.09	1.09
module for Ethernet Driver and Embedded																								
system M3S-T4-Tiny	D004110000	4.00	1.01																					
Embedded TCP/IP M3S-T4-Tiny Socket API Module	R20AN0296	1.30	1.31	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
System Timer Module	R20AN0431	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01
SX-ULPGN-2000 Wi- Fi Module Control	R01AN4664	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.13	1.14
Module BLE Module (BLE)	R01AN4860	_	-	_	-	-	_	_	-	_	_	_	-	1.01	1.01	1.10	1.10	2.00	2.10	2.11	2.20	2.20	2.30	2.30
RYZ012 Bluetooth	R01AN6290	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		1.01
Low Energy Module  QE Utility Module	R01AN4907													0.00	1.00	1.00	1.00	1.00	1 00	1.00	1.00	1.00	1 10	1 10
(Profiles)	NO PAINESU/	L																						
Mesh Module (Mesh)	R01AN4930	-	-	-	-	-	-	-	-	-	-		-	1.00	1.01	1.01	1.01	1.10	1.10	1.10	1.10	1.10	1.20	
RYZ014A Cellular Module	R01AN6324		-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.04
SD memory card driver module	R01AN4233	-	-	-	-	-	-	2.02	2.03	2.03	2.03	2.03	2.03	2.03	2.03	3.00	3.00	3.00	3.00	3.00	3.00	3.00	3.00	3.00
Flash Memory Data Management Module	R20AN0507	-	-	-	-	-	-	-	-	-	-	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01
Clock Synchronous Control Module for	R01AN2662	2.33	2.33	2.33	2.34	2.34	2.34	2.34	2.34	2.34	3.00	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.02	3.02	3.02	3.03	3.03
Serial Flash Memory Access																								
Clock Synchronous Control Module for EEPROM Access	R01AN2325	2.33	2.33	2.33	2.34	2.34	2.34	2.34	2.34	2.34	3.00	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.02	3.02	3.02	3.02	3.02
Memory Access	R01AN4548	-	-	-	-	-	-	-	-	-	1.00	1.01	1.01	1.01	1.02	1.02	1.02	1.03	1.03	1.03	1.03	1.03	1.04	1.04
Driver Interface Module																								
JPEG Decoder Module	R20AN0104	-	-																	2.06				
JPEG Encoder Module	R20AN0263	-	-																	1.01				
Sound Playback/Compressio n System (Original ADPCM Codec) [M3S-S2-Tiny] Module	R20AN0037	3.03	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04
Open Source FAT File System [M3S-TFAT-Tiny]	R20AN0038	3.02	3.03	3.03	3.03	3.03	3.03	3.03	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	4.00	4.01	4.01	4.02	4.02	4.02	4.02	4.02
Module M3S-TFAT-Tiny	R20AN0335	1.02	1.03	1.03	1.03	1.03	1.03	1.04	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	2.00	2.10	2.10	2.20	2.20	2.20	2.20	2.20
Memory Driver Interface Module																								
Firmware Update Module	R01AN5824		-	-	_	_	_	-	_	_	-	_	-	_	_	_	_	-	Ĺ				1.02	
Sensor Communication	R01AN5895	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	1.00	1.20	1.21
Middleware Control Module																								
HS300x Sensor Control Module	R01AN5893	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	1.10	1.11	1.22
FS2012 Sensor	R01AN6045	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.01	1.02
Control Module ZMOD4410 and ZMOD4510 Sensor	R01AN6046	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.10	1.20
Control Module	<u> </u>	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L		L	L			
QE Touch Module	R01AN4470	-	-	-	-	-	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.10	1.10	1.11	1.11	1.11	1.11				_
Aeropoint module emWin v.6.14 module	R01AN5793	-	-	-	-  -	-  -	-	-	-  -	-	-	-	-	-	<u>-</u>	-  -	-  -	- 1 10	1 10	1.00			1.00	1.00
emWin v.6.22 module		-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.10	-	-	-	-	1.00	1.00
-		•	•		•	•			•				•		•	•	•		•	-	•	•		

### **Revision History**

		Descript	ion
Rev.	Date	Page	Summary
1.00	Aug. 31. 2021	_	First edition issued
1.01	Apr. 13. 2022	3-4	Table 1.2 Deleted v1.21 and added V1.33 and V1.34.
			Modified content.
		5-6	Table 2.2 Deleted v1.21 and added V1.33 and V1.34.
			Modified content.

# General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

- 6. Voltage application waveform at input pin
  - Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).
- 7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not quaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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